

Feature

The KE-2050 is typically used as a compliment to the KE-2060 to increase overall throughput by placing the higher volume small chip components SOTs and ICs.

- 13,200CPH: chip (laser centering/effective tact)
- One multi-nozzle laser head (4 nozzles)
- from 0603 (0201) to 20mm square components or 26.5×11mm 0402 (01005) option factory installed.

※1 Actual throughput may vary.

※2 Please download brochure for details.



Specifications

Board size	M size (330×250mm)	○
	L size (410×360mm)	○
	L-wide (510×360mm)	○
	E size (510×460mm)	-
Component size	Laser recognition	0603 ~ □20mm or 26.5×11mm (0402 (01005) optional)*2
Placement speed	Chip	13,200CPH*1
Placement accuracy	Laser recognition	±0.05mm
Feeder inputs		Max. 80 on 8mm T/F

※1 Effective tact: The chip placement speed indicates an estimated value obtained when the machine places 400 1608-chips all over an M size board.

(CPH = number of components placed for one hour)

※2 Please ask for details on 0402(01005) placement.